

Type number	Package	Package description	Total product weight
74LV123DB	SOT338-1	SSOP16	127.37742 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator	
		MSL	PPT	MPPT	MSL	PPT	MPPT			IMG	6
935210260118	12	1	260	30 s	1	240	20 s	3	Nijmegen, Netherlands; Suzhou, China; Bangkok, Thailand	IMG	6

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Adhesive	Filler	Silver (Ag)	7440-22-4	7.50000	75.00000	5.88801
	Polymer	Resin system	Proprietary	2.50000	25.00000	1.96267
		subTotal		10.00000	100.00000	7.85068
Die	Doped silicon	Silicon (Si)	7440-21-3	0.85796	100.00000	0.67356
		subTotal		0.85796	100.00000	0.67356
Lead Frame Material	Copper alloy	Copper (Cu)	7440-50-8	47.87726	97.47000	37.58693
		Iron (Fe)	7439-89-6	1.17888	2.40000	0.92550
		Phosphorous (P)	7723-14-0	0.01474	0.03000	0.01157
		Zinc (Zn)	7440-66-6	0.04912	0.10000	0.03856
		subTotal		49.12000	100.00000	38.56256
Mould Compound	Filler	Misc. Silica compounds (generic)	14808-60-7	50.25000	75.00000	39.44969
	Flame retardant	Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	1.47400	2.20000	1.15719
		Misc. Bromine compounds (generic)	7726-95-6	1.07200	1.60000	0.84159
	Polymer	Epoxy resin system	Proprietary	14.20400	21.20000	11.15111
	subTotal		67.00000	100.00000	52.59958	
Pre-Plating	Pure metal layer	Gold (Au)	7440-57-5	0.00200	1.00000	0.00157
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.19400	97.00000	0.15230
		Palladium (Pd)	7440-05-3	0.00400	2.00000	0.00314
		subTotal		0.20000	100.00000	0.15701
Wire	Pure metal	Gold (Au)	7440-57-5	0.19746	99.00000	0.15502
		Palladium (Pd)	7440-05-3	0.00199	1.00000	0.00157
		subTotal		0.19946	100.00000	0.15659

#### Note(s):

1) This is a generic description of the substance used as the actual composition of the substances are either considered proprietary or no official CAS number is available. If a CAS number is given, it is the closest match available.

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